

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6215xxxxHR-G
Typical Mass: 2.5 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.197	Silicon	78800	7440-21-3
	-	Arsenic	5	7440-38-2
Lead pad	0.491	Nickel	196400	7440-02-0
	0.023	Silver	9100	7440-22-4
	0.005	Gold	2000	7440-57-5
Die attach(1)	0.014	Epoxy Resin	5400	—
	0.011	Silica	4500	60676-86-0
Bonding wire	0.035	Gold	14200	7440-57-5
Resin	1.509	Silica	603700	60676-86-0
	0.086	Epoxy Resin	34400	—
	0.077	Phenol Resin	30800	—
	0.052	Metal Hydroxide	20700	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."

* The composition for the die attach types is either (1) or (2).